

ABSTRACT OF THE DISCLOSURE

A high-frequency circuit formed on a surface of a dielectric substrate includes: a signal strip formed on a first face of the dielectric substrate for transmitting a signal therethrough; a pair of ground strips formed on the first face astride the signal strip, with an interspace on each side of the signal strip; a ground conductor layer formed on a second face of the dielectric substrate, the second face being opposite to the first face; and a plurality of through-vias formed in the dielectric substrate astride the signal strip for electrically connecting the pair of ground strips to the ground conductor layer. First and second through-vias, which are a pair of opposing through-vias located closest to a terminating end of the signal strip, are disposed apart from each other by a distance smaller than a distance between any other pair of opposing through-vias.